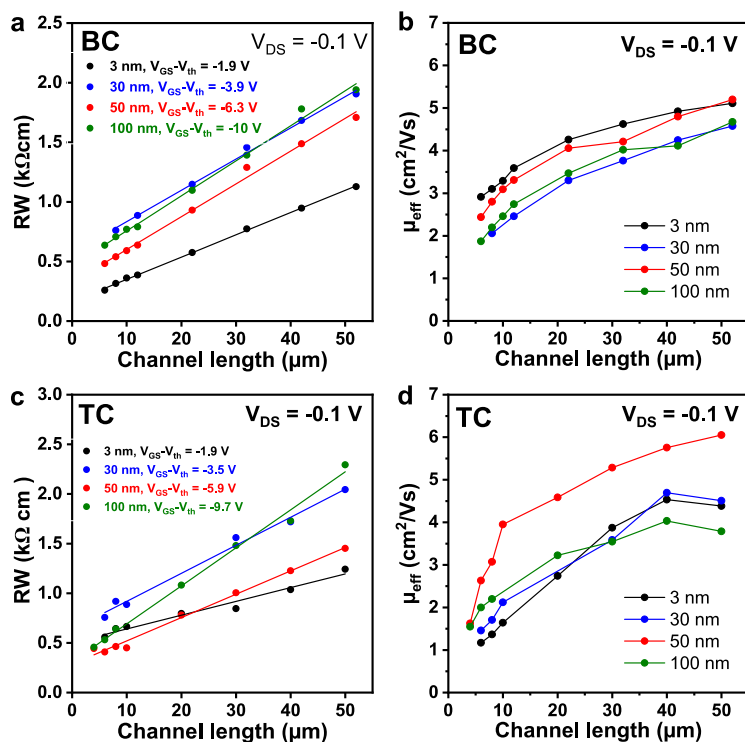


**Supplementary Information**

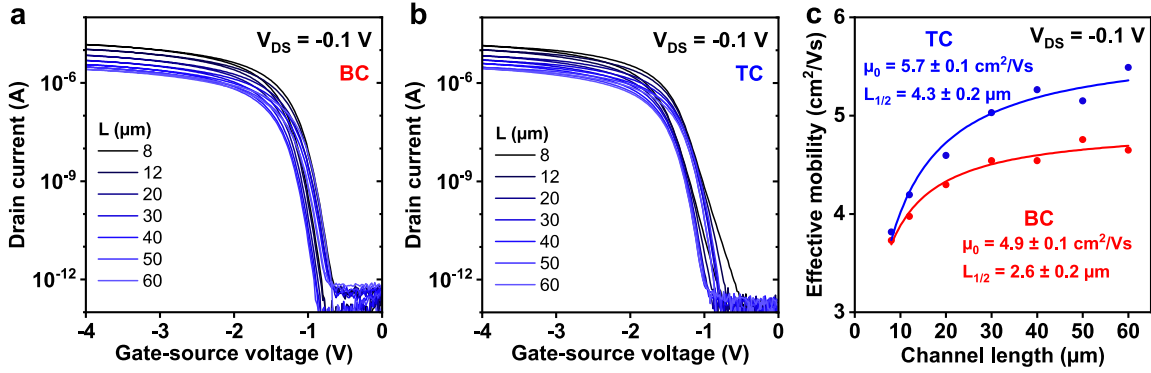
**Small contact resistance and high-frequency operation of flexible low-voltage inverted coplanar organic transistors**

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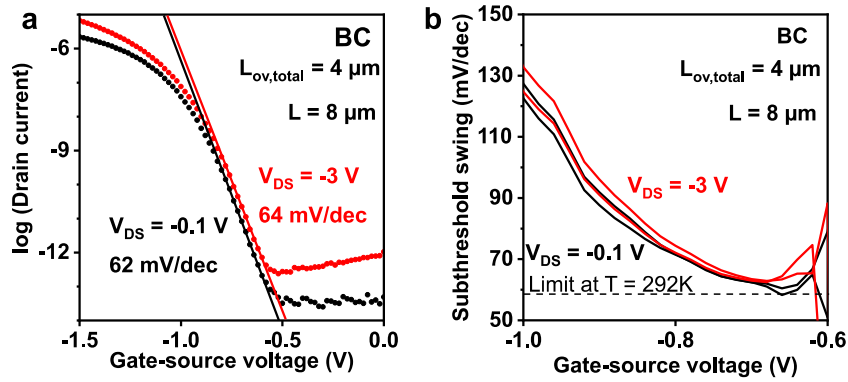
## Supplementary Figures



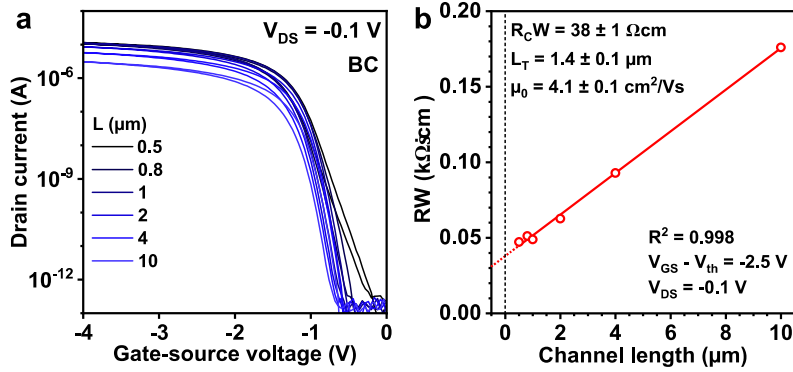
**Figure 1: Analysis of DPH-DNTT TFTs with different gate-dielectric thicknesses.** The bottom contact (BC) and top contact (TF) TFTs are fabricated on highly-doped silicon substrates and have SAM-modified atomic-layer-deposited  $\text{Al}_2\text{O}_3$  gate dielectrics with gate-oxide thicknesses of 3, 30, 50 and 100 nm, channel lengths ranging from 4 to 50  $\mu\text{m}$ , and a channel width of 200  $\mu\text{m}$ . (a,c) Transmission line method (TLM) analysis performed at the largest gate overdrive voltage for each gate-oxide thickness. All fits show  $R^2 > 0.9$ . (b,d) Effective carrier mobility plotted as a function of the channel length.



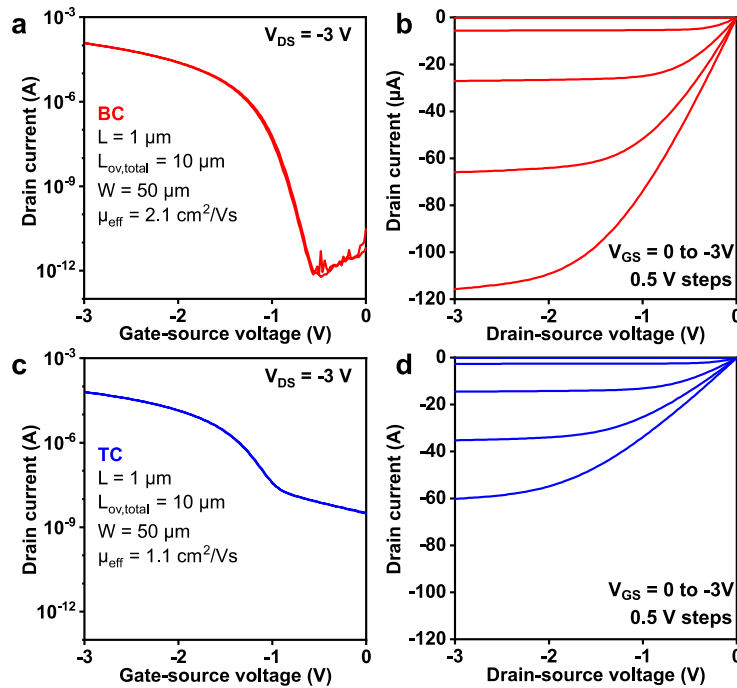
**Figure 2: DPh-DNTT TFTs fabricated on flexible PEN substrates.** The TFTs have channel lengths ranging from 8 to 60  $\mu\text{m}$ , a channel width of 200  $\mu\text{m}$ , and a total gate-to-contact overlap of 10  $\mu\text{m}$ . (a) Transfer characteristics of the bottom-contact TFTs. (b) Transfer characteristics of the top-contact TFTs. The transfer data from a and b was employed for the TLM analysis reported in Figure 5 and Table 1 of the main manuscript. (c) Effective carrier mobility ( $\mu_{eff}$ ) plotted as a function of the channel length. The data are fit to the equation  $\mu_{eff} = \mu_0 / (1 + L_{1/2} / L)$ , where  $\mu_0$  is the intrinsic channel mobility,  $L$  is the channel length, and  $L_{1/2}$  is the channel length at which  $\mu_{eff} = \frac{1}{2} \mu_0$ .



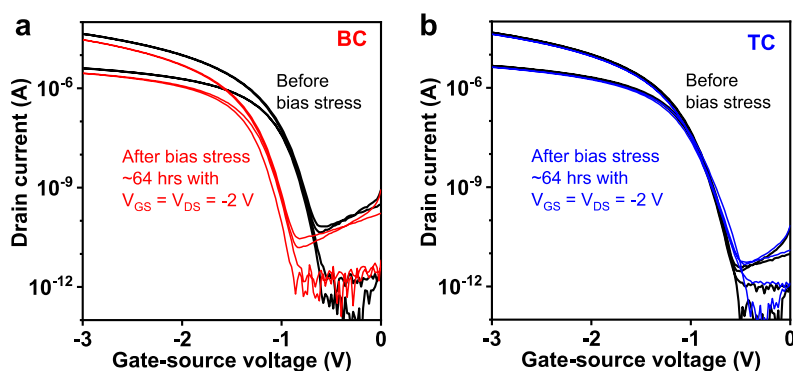
**Figure 3: Subthreshold characteristics of bottom-contact DPh-DNTT TFTs fabricated on flexible PEN.** The TFTs have a channel length of 4  $\mu\text{m}$ , a channel width of 200  $\mu\text{m}$ , and a total gate-to-contact overlap of 4  $\mu\text{m}$ . (a) Exponential fit to the subthreshold region of the transfer characteristics of the TFT with the steepest subthreshold swing, yielding subthreshold swings of 62 and 64 mV/decade at drain-source voltages of -0.1 and -3 V, respectively. (b) Derivative of the measured transfer curves plotted as a function of the gate-source voltage. The dotted line denotes the theoretical limit of the subthreshold swing at a temperature of 292 K, i.e., 58 mV/decade.



**Figure 4: Bottom-contact DPh-DNTT TFTs with short channel lengths fabricated on a PEN substrate.** (a) Measured transfer curves of the short-channel bottom-contact DPh-DNTT TFTs fabricated on flexible PEN substrates employed for the TLM analysis reported in **Figure 7** of the main manuscript. The TFTs have channel lengths ranging from 0.5 to 10  $\mu\text{m}$ , a channel width of 50  $\mu\text{m}$ , and a total contact overlap length of 10  $\mu\text{m}$ . (b) TLM analysis performed at the largest gate overdrive voltage.



**Figure 5: DPh-DNTT TFTs with a channel length of 1  $\mu\text{m}$  fabricated on PEN substrates.** (a,c) Transfer and (b,d) output characteristics of bottom-contact and top-contact DPh-DNTT TFTs fabricated on flexible polyethylene naphthalate (PEN) substrates having a channel length of 1  $\mu\text{m}$ , a channel width of 50  $\mu\text{m}$ , and a total gate overlap length of 10  $\mu\text{m}$ .



**Figure 6: Bias-stress stability of DPh-DNTT TFTs fabricated on a silicon substrate.** These TFTs were fabricated by depositing a 30-nm-thick aluminum gate electrode onto the doped silicon substrate and then forming a 3.6-nm-thick layer of aluminum oxide by oxygen-plasma growth and a 1.7-nm-thick *n*-tetradecylphosphonic acid self-assembled monolayer from solution to obtain a 5.4-nm-thick  $\text{AlO}_x/\text{SAM}$  gate dielectric. The TFTs have a channel length of 20  $\mu\text{m}$  and a channel width of 200  $\mu\text{m}$ . The bias stress was performed by applying gate-source and drain-source voltages of -2 V continuously for a duration of 64 hours in ambient air. The effective carrier mobility of the bottom-contact TFT (a) was 3.5  $\text{cm}^2/\text{Vs}$  prior to and 3.0  $\text{cm}^2/\text{Vs}$  after the bias-stress experiment. The effective mobility of the top-contact TFT (b) was 3.7  $\text{cm}^2/\text{Vs}$  prior to and 3.5  $\text{cm}^2/\text{Vs}$  after the bias-stress experiment.